FOR IMMEDIATE RELEASE

EV GROUP GEMINI WAFER BONDER TO BE IMPLEMENTED AT QUEBEC'S STATE-OF-THE-ART MIQRO INNOVATION COLLABORATIVE CENTRE

EVG System to Play Vital Role in Enabling Joint-Partnership R&D Facility's Focus on MEMS and Wafer-Level Packaging and Integration Solutions

ST. FLORIAN, Austria, June 28, 2011 – EV Group (EVG), a leading supplier of wafer bonding and lithography equipment for the MEMS, nanotechnology and semiconductor markets, today announced it has received an order for its Gemini fully automated wafer-bonding system. The Gemini system will be installed at the MiQro Innovation Collaborative Centre (C2MI), which is currently under construction in Technoparc Bromont (Quebec, Canada).

The 200-mm Gemini platform to be installed at C2MI can handle up to four pre-processing modules and incorporates EVG's latest software and control system. It also features a cleaner module that will be used to control particulate levels in the tool and for post-processing efforts. The Gemini system will be used to develop and produce devices to demonstrate advanced packaging of MEMS devices and full integration of CMOS and MEMS devices, with the end goal of successful transfer to high-volume manufacturing (HVM) scenarios. Examples of end products include pressure sensors, inertial sensors, RF MEMS devices, telecommunications MEMS sensors, microfluidics and imaging sensors.

Luc Ouellet, Teledyne DALSA's vice president of technology development, stated, "The state-of-the-art C2MI facility is being developed to serve as an international reference in scientific research and development in the fields of packaging of complex microsystems, 3D design integration and MEMS, developing prototypes that will help accelerate commercialization of these solutions for a range of applications. To achieve these goals requires implementation of the industry's best-in-class equipment, and, as we can attest, EVG's Gemini system certainly qualifies in this regard."

A range of factors contributed to the selection of the EVG Gemini system over competitive offerings—in particular, its ability to meet the facility's aggressive technical specifications, throughput and productivity requirements. In addition, EVG demonstrated its ability to deliver a flexible, cost-effective solution optimized for scalability and low cost of ownership, as well as its extensive capabilities in MEMS, HVM, wafer-level packaging and integration, 3D integration and through-silicon vias (TSVs).

Steven Dwyer, EV Group's vice president and general manager, North America, said, "This order represents a key next step in the deployment of our Gemini wafer-bonding technology. Our proven success with a 150-mm system at Teledyne DALSA helped spur the decision to purchase a Gemini system for C2MI, which will essentially be a 200-mm version of the 300-mm Gemini platform installed at SEMATECH's 3D R&D Center in Albany, N.Y. This will provide a great opportunity for EVG to pursue high-volume wafer-level integration of 200-mm MEMS devices, strengthening our presence in key target markets and broadening our exposure to customers of this new, leading-edge venture."

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About C2MI
The MiQro Innovation Collaborative Centre (C2MI) is an original partnership between Université de Sherbrooke, Teledyne DALSA Inc. and IBM Canada Ltd, Bromont Plant. The C2MI will be an international pioneer in packaging the next generation of microchips and designing packages for future generations of microelectromechanical systems (MEMS). Together, these founding partners have created an ecosystem which will facilitate recruiting other industrial and academic partners. The initial investment (building and research equipment) of $218.45 million is supported by Industry Canada, ministère du Développement économique, de l'Innovation et de l'Exportation du Québec, the town of Bromont, the founding partners and equipment suppliers. Visit www.c2mi.ca.

About EV Group
EV Group (EVG) is a world leader in wafer-processing solutions for semiconductor, MEMS and nanotechnology applications. Through close collaboration with its global customers, the company implements its flexible manufacturing model to develop reliable, high-quality, low-cost-of-ownership systems that are easily integrated into customers' fab lines. Key products include wafer bonding, lithography/nanoimprint lithography (NIL) and metrology equipment, as well as photoresist coaters, cleaners and inspection systems.

In addition to its dominant share of the market for wafer bonders, EVG holds a leading position in NIL and lithography for advanced packaging and MEMS. Along these lines, the company co-founded the EMC-3D consortium in 2006 to create and help drive implementation of a cost-effective through-silicon via (TSV) process for major ICs and MEMS/sensors. Other target semiconductor-related markets include silicon-on-insulator (SOI), compound semiconductor and silicon-based power-device solutions.

Founded in 1980, EVG is headquartered in St. Florian, Austria, and operates via a global customer support network, with subsidiaries in Tempe, Ariz.; Albany, N.Y.; Yokohama and Fukuoka, Japan; Seoul, Korea and Chung-Li, Taiwan. The company's unique Triple i-approach (invent - innovate - implement) is supported by a vertical integration, allowing EVG to respond quickly to new technology developments, apply the technology to manufacturing challenges and expedite device manufacturing in high volume. More information is available at www.EVGroup.com.

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